

Attorney Docket No.: <u>SSI-02001</u>

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Maximilian A. Biberger et al.

Serial No.: 09/841,800

Filed: April 24, 2001

For:

METHOD OF DEPOSITING METAL FILM AND METAL DEPOSITION CLUSTER TOOL INCLUDING SUPERCRITICAL DRYING/CLEANING MODULE

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313 Group Art Unit: 2825

Examiner: Everhart, Caridad

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

162 N. Wolfe Road Sunnyvale, CA 94086 (408) 530-9700

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Sir:

The citations listed below, copies attached, may be material to the examination of the above-identified application, and are therefore submitted in compliance with the duty of disclosure defined in 37 C.F.R. §§ 1.56 and 1.97. The Examiner is requested to make these citations of official record in this application.

United States Patents or Published Patent Applications have been filed electronically (EFS ID #50637); (EFS ID #50638); (EFS ID #50639); (EFS ID #50640); and (EFS ID #50641). Applicants have become aware of the following printed publication which may be material to the examination of this application:

- German Publication No. DE 39 04 514 C2;
- German Publication No. DE 39 06 724 C2;
- German Publication No. DE 39 06 735 C2;
- German Publication No. DE 39 06 737 A1;
- German Publication No. DE 40 04 111 C2;
- German Publication No. DE 43 44 021 A1;
- German Publication No. DE 44 29 470 A1;
- European Publication No. EP 0 518 653 B1;
- European Publication No. EP 0 620 270 A3;

- European Publication No. EP 0 679 753 A1;
 European Publication No. EP 0 711 864 B1;
- Japanese Patent Abstract JP 1-246835;
- Japanese Patent Abstract JP 8-186140;
- PCT Publication No. WO 93/14255;
- PCT Publication No. WO 93/14259;
- PCT Publication No. WO 93/20116;
- PCT Publication No. WO 96/27704;
- PCT Publication No. WO 00/73241 A1;
- PCT Publication No. WO 02/09894 A2;
- PCT Publication No. WO 02/11191 A2;
- PCT Publication No. WO 02/16051 A2;
- "Porous Xerogel Films as Ultra-Low Permittivity Dielectrics for ULSI
 Interconnect Applications", Materials Research Society, pp. 463-469, 1997;
- Kawakami et al, "A Super Low-k (k=1.1) Silica Aerogel Film Using Supercritical Drying Technique", IEEE, pp. 143-145, 2000;
- R.F. Reidy, "Effects of Supercritical Processing on Ultra Low-K Films", Texas Advanced Technology Program, Texas Instruments, and the Texas Academy of Mathematics and Science;
- Anthony Muscat, "Backend Processing Using Supercritical CO2", University of Arizona;
- D. Goldfarb et al., "Aqueous-based Photoresist Drying Using Supercritical Carbon Dioxide to Prevent Pattern Collapse", J. Vacuum Sci. Tech. B 18 (6), 3313 (2000);
- H. Namatsu et al., "Supercritical Drying for Water-Rinsed Resist Systems", J.
 Vacuum Sci. Tech. B 18 (6), 3308 (2000); and
- N. Sundararajan et al., "Supercritical CO2 Processing for Submicron Imaging of Fluoropolymers", Chem. Mater. 12, 41 (2000).

<u>PATENT</u> Attorney Docket No.: SSI-02001

This Supplemental Information Disclosure Statement under 37 C.F.R. §§ 1.56 and 1.97 is not to be construed as a representation that a search has been made, that additional information material to the examination of this application does not exist, or that anyone or more of these citations constitutes prior art.

Respectfully submitted,

HAVERSTOCK & OWENS LLP

Reg. No.: 32,571

Attorneys for Applicants

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Applicants: Maximilian A. Biberger et al.

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